

# 3A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low profile package
- Ultra Fast recovery time for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer and telecommunication.

#### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.200g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	3	Α	
$V_{RRM}$	100 - 200	V	
I <sub>FSM</sub>	125	Α	
T <sub>J MAX</sub>	175	°C	
Package	DO-214AB (SMC)		
Configuration	Single die		









DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	ESH3B	ESH3C	ESH3D	UNIT
Marking code on the device		ESH3B	ESH3C	ESH3D	
Repetitive peak reverse voltage	$V_{RRM}$	100	150	200	V
Reverse voltage, total rms value	$V_{R(RMS)}$	70	105	140	V
Forward current	I <sub>F</sub>	3		Α	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	125		А	
Junction temperature	$T_J$	- 55 to +175		°C	
Storage temperature	T <sub>STG</sub>		- 55 to +175		°C



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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	R <sub>OJL</sub>	12	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	47	°C/W

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 3A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	0.9	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C	ı	-	5	μΑ
	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	150	μΑ
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	CJ	45	-	pF
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t <sub>rr</sub>	-	20	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
ESH3x	DO-214AB (SMC)	3,000 / Tape & Reel	

### Notes:

1. "x" defines voltage from 100V(ESH3B) to 200V(ESH3D)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

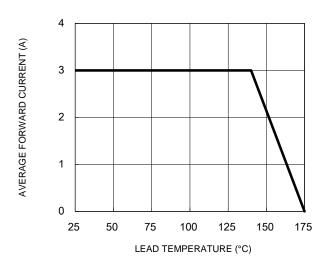


Fig.3 Typical Reverse Characteristics

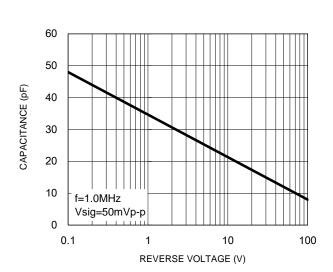
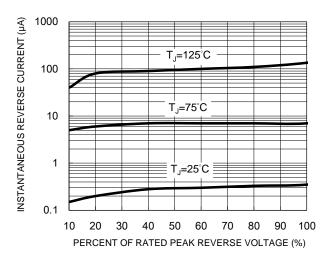


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



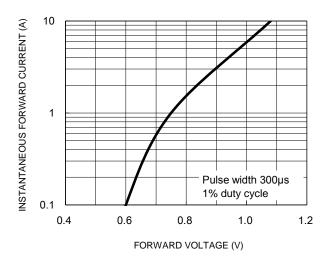
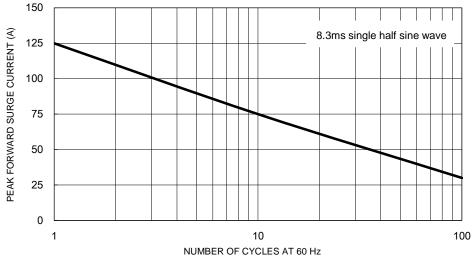


Fig.5 Maximum Non-Repetitive Forward Surge Current



3

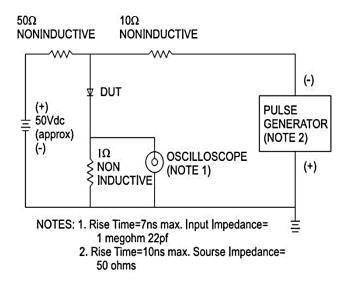


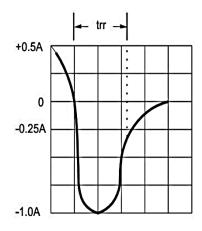


### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram



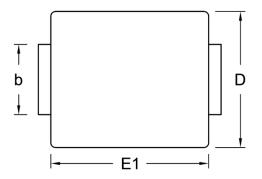


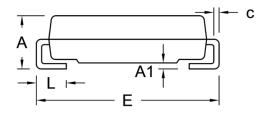




# **PACKAGE OUTLINE DIMENSIONS**

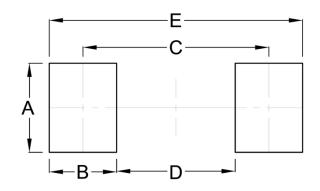
## DO-214AB (SMC)





DIM.	Unit (mm)		Unit (	(inch) Max.	
Dilvi.	Min.	Min. Max.			
Α	2.00	2.62	0.079	0.103	
A1	0.10	0.20	0.004	0.008	
b	2.90	3.20	0.114	0.126	
С	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

## **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

YW = Date Code F = Factory Code



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